

US Patent Application  
Title: Resin Particle, Conductive Particle, And Anisotropic  
Conductive Adhesive Containing The Same  
WELSH & KATZ, LTD.  
Docket No. 9155-93354 Sheet 1 of 6

FIG. 1

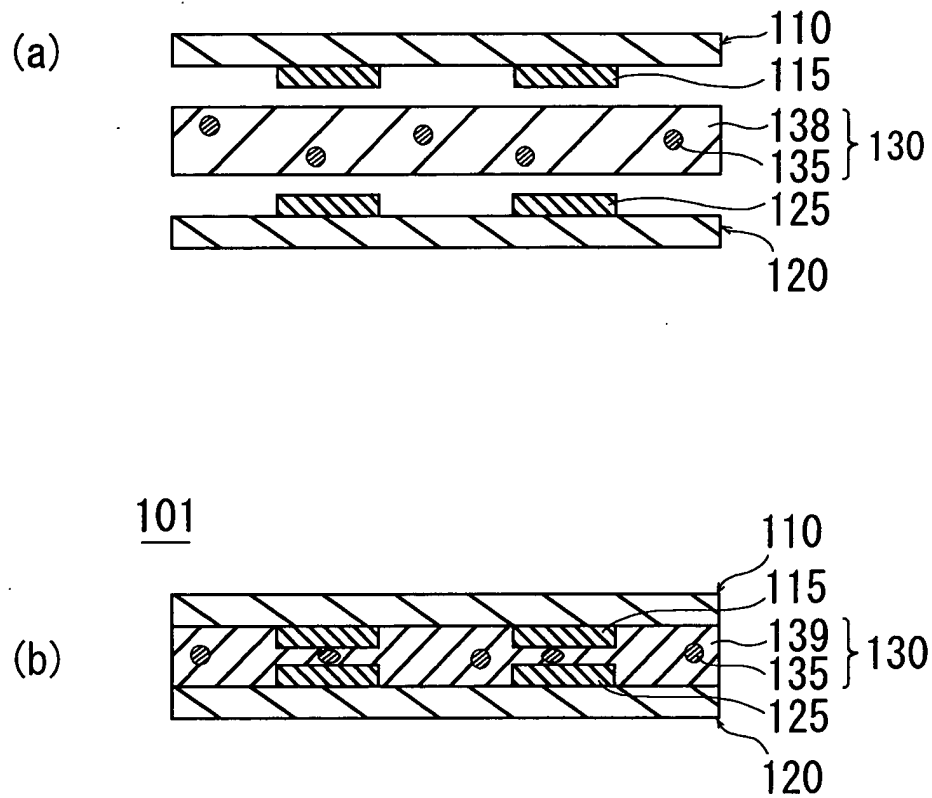


FIG. 2

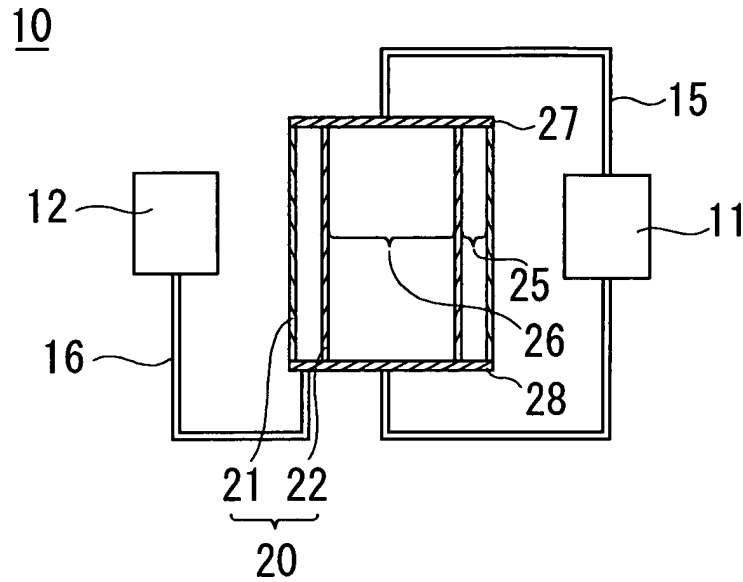


FIG. 3

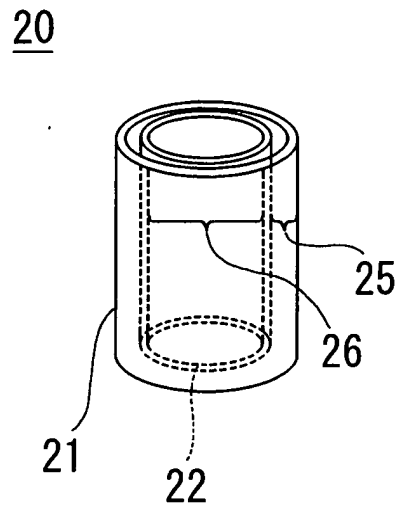


FIG. 4

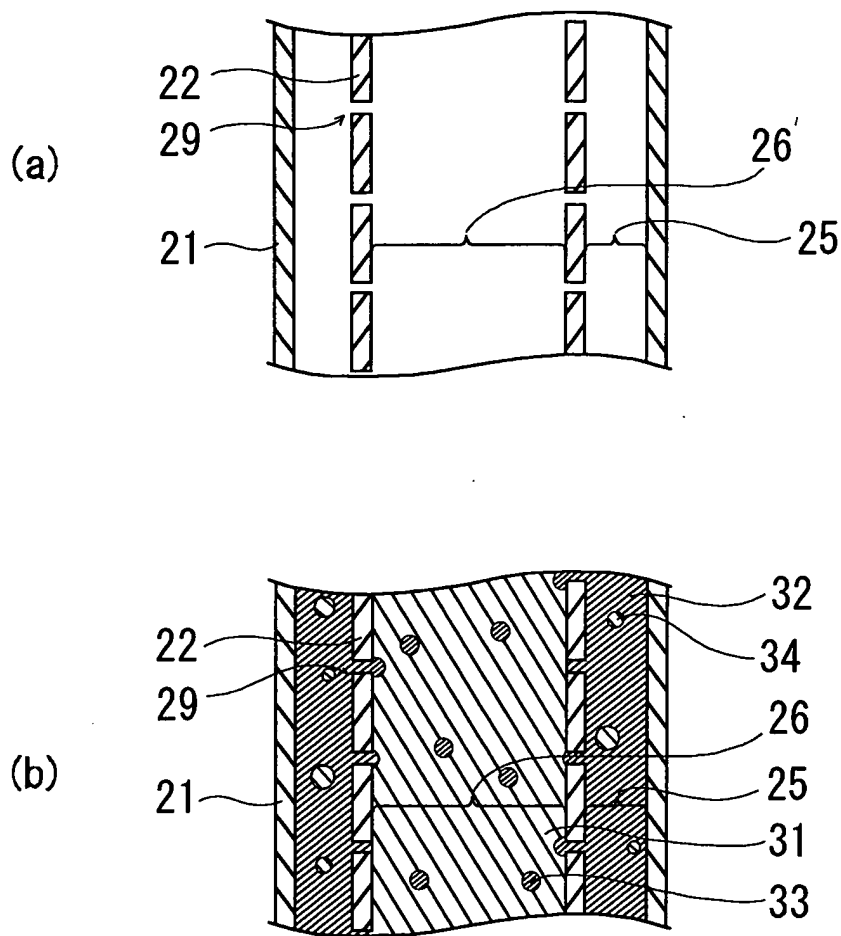
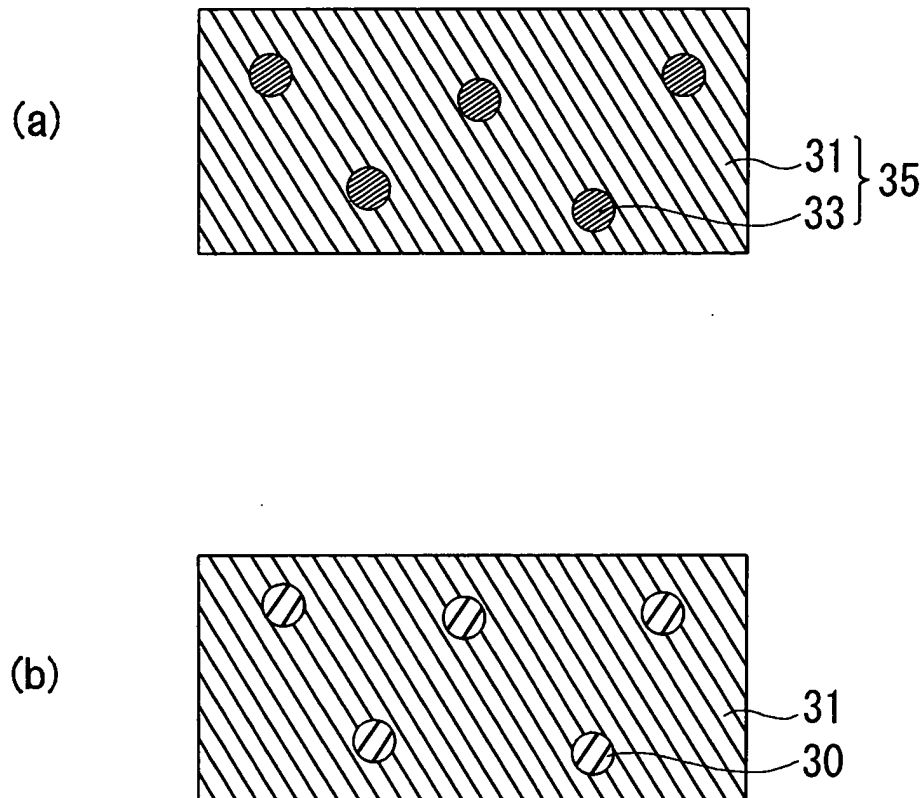
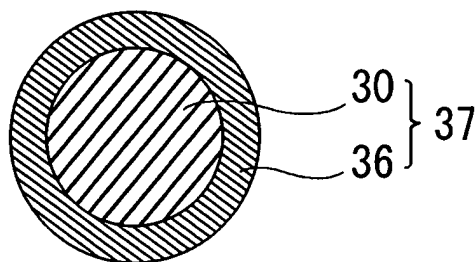


FIG. 5



F I G. 6



F I G. 7

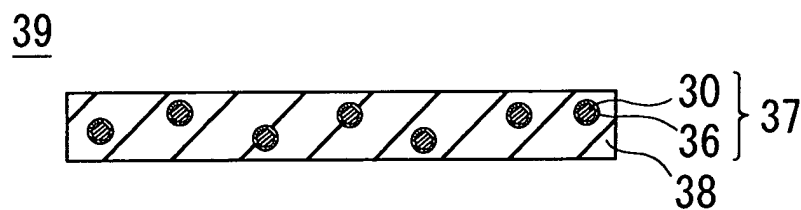


Figure 1 consists of three cross-sectional views of a semiconductor device, labeled (a), (b), and (c).

- (a)** Shows a substrate 41 with a top layer 42. A patterned layer 43 is formed on the top layer 42. A layer 39 is formed on the patterned layer 43, containing circular features 30. A layer 45 is formed on the layer 39, containing circular features 36. A layer 46 is formed on the layer 45, containing circular features 37. A layer 47 is formed on the layer 46, containing circular features 38.
- (b)** Shows the device after a second layer 44 has been formed on the layer 43, between the patterned layer 43 and the layer 45. The layer 44 contains circular features 37. The layer 45 contains circular features 36. The layer 46 contains circular features 37. The layer 47 contains circular features 38.
- (c)** Shows the device after a third layer 40 has been formed on the layer 44, between the layer 44 and the layer 45. The layer 40 contains circular features 37. The layer 44 contains circular features 37. The layer 45 contains circular features 36. The layer 46 contains circular features 37. The layer 47 contains circular features 38.